

RD Number: RD101

RD Title: TB67H410NG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	VM	1	Check terminal	-	-	Check pin		
2	VCC	1	Check terminal	-	-	Check pin		
3	VDD	1	Check terminal	-	-	Check pin		
4	HBMODE	1	Check terminal	-	-	Check pin		
5	VREF	1	Check terminal	-	-	Check pin		
6	OSCM	1	Check terminal	-	-	Check pin		
7	INA1	1	Check terminal	-	-	Check pin		
8	INA2	1	Check terminal	-	-	Check pin		
9	PWMA	1	Check terminal	-	-	Check pin		
10	PWMB	1	Check terminal	-	-	Check pin		
11	INB1	1	Check terminal	-	-	Check pin		
12	INB2	1	Check terminal	-	-	Check pin		
13	TBLKAB	1	Check terminal	-	-	Check pin		
14	RSA	1	Check terminal	-	-	Check pin		
15	RSB	1	Check terminal	-	-	Check pin		
16	OUT_A+	1	Check terminal	-	-	Check pin		
17	OUT_A-	1	Check terminal	-	-	Check pin		
18	OUT_B+	1	Check terminal	-	-	Check pin		
19	OUT_B-	1	Check terminal	-	-	Check pin		
20	GND1	1	Check terminal	-	-	Check pin		
21	GND2	1	Check terminal	-	-	Check pin		
22	GND3	1	Check terminal	-	-	Check pin		
23	GND4	1	Check terminal	-	-	Check pin		
24	GND5	1	Check terminal	-	-	Check pin		
25	GND6	1	Check terminal	-	-	Check pin		
26	RRSA	1	0.22Ω 1W	-	-	Chip resistor		

27	RRSB	1	0.22Ω 1W	–	–	Chip resistor		
28	RVRF1	2	Socket pin	–	–	Socket pin		
29		0	Not mount	–	–	Leaded resistor		✓
30	RVRF2	2	Socket pin	–	–	Socket pin		
31		0	Not mount	–	–	Leaded resistor		✓
32	ROSCM	0	Socket pin	–	–	Socket pin		✓
33		0	5.1kΩ	–	–	Leaded resistor		✓
34		1	5.1kΩ 0.25W	–	–	Resistor		
35	COSCM	0	Socket pin	–	–	Socket pin		✓
36		0	270pF	–	–	Leaded capacitor		✓
37		1	270pF 1000V	–	–	Chip capacitor		
38	CVRF1	1	0.1μF 100V	–	–	Chip capacitor		
39	CVRF2	0	0.1μF 100V	–	–	Chip capacitor		✓
40	CVCC	1	0.1μF 100V	–	–	Chip capacitor		
41	CVM3	0	0.1μF 100V	–	–	Chip capacitor		✓
42	CVM2	1	0.1μF 100V	–	–	Chip capacitor		
43	CVM1	1	100μF 50V	–	–	Electrolytic capacitor		
44	CVDD	0	10μF 10V	–	–	Electrolytic capacitor		✓
45	JP1	1	Pin header 2P	–	–	Jumper		
46		1	Jumper socket	–	–	Jumper Short		
47	JP2	1	Pin header 2P	–	–	Jumper		
48		1	Jumper socket	–	–	Jumper Short		
49	SW1(HBMODE)	1	Pin header 3P	–	–	Jumper		
50		1	Jumper socket	–	–	Jumper Short		
51	SW2(INA1)	1	Pin header 3P	–	–	Jumper		
52		1	Jumper socket	–	–	Jumper Short		
53	SW3(INA2)	1	Pin header 3P	–	–	Jumper		
54		1	Jumper socket	–	–	Jumper Short		
55	SW4(PWMA)	1	Pin header 3P	–	–	Jumper		
56		1	Jumper socket	–	–	Jumper Short		
57	SW5(PWMB)	1	Pin header 3P	–	–	Jumper		
58		1	Jumper socket	–	–	Jumper Short		
59	SW6(INB1)	1	Pin header 3P	–	–	Jumper		
60		1	Jumper socket	–	–	Jumper Short		

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